## SESSION 17: DEVICE PACKAGING INNOVATION

Chair: Zaher Bardai, *Epiphany*

This session will focus on packaging developments for III-V devices, extending from RFMEMS switches and low phase noise oscillators to high speed communication integrated circuits and high power GaN devices. The discussions will include wafer level packaging using adhesive bonding techniques, semiconductor and Pyrex glass caps, flip-chip assemblies, polymer cavity structures that provide high humidity resistance in operating environments and, the use of silver diamond base materials for high power applications.